



# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 1K Microwire Compatible Serial EEPROM

Device Selection Table

Part Number	Vcc Range	ORG Pin	Word Size	Temp Ranges	Packages
93AA46A	1.8-5.5	No	8-bit	I	P, SN, ST, MS, OT
93AA46B	1.8-5.5	No	16-bit	I	P, SN, ST, MS, OT
93LC46A	2.5-5.5	No	8-bit	I, E	P, SN, ST, MS, OT
93LC46B	2.5-5.5	No	16-bit	I, E	P, SN, ST, MS, OT
93C46A	4.5-5.5	No	8-bit	I, E	P, SN, ST, MS, OT
93C46B	4.5-5.5	No	16-bit	I, E	P, SN, ST, MS, OT
93AA46C	1.8-5.5	Yes	8 or 16-bit	I	P, SN, ST, MS
93LC46C	2.5-5.5	Yes	8 or 16-bit	I, E	P, SN, ST, MS
93C46C	4.5-5.5	Yes	8 or 16-bit	I, E	P, SN, ST, MS

### Features

- Low-power CMOS technology
- ORG pin to select word size for '46C version
- 128 x 8-bit organization 'A' ver. devices (no ORG)
- 64 x 16-bit organization 'B' ver. devices (no ORG)
- Self-timed ERASE/WRITE cycles (including auto-erase)
- Automatic ERAL before WRAL
- Power-on/off data protection circuitry
- Industry standard 3-wire serial I/O
- Device Status signal (READY/BUSY)
- Sequential READ function
- 1,000,000 E/W cycles
- Data retention > 200 years
- Temperature ranges supported
  - Industrial (I) -40°C to +85°C
  - Automotive (E) -40°C to +125°C

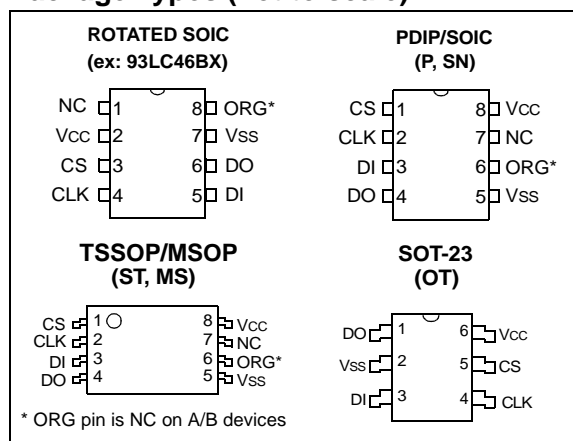
### Pin Function Table

Name	Function
CS	Chip Select
CLK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
Vss	Ground
NC	No internal connection
ORG	Memory Configuration
Vcc	Power Supply

### Description

The Microchip Technology Inc. 93XX46A/B/C devices are 1K bit low voltage serial Electrically Erasable PROMs (EEPROM). Word-selectable devices such as the 93AA46C, 93LC46C or 93C46C are dependent upon external logic levels driving the ORG pin to set word size. For dedicated 8-bit communication, the 93AA46A, 93LC46A or 93C46A devices are available, while the 93AA46B, 93LC46B and 93C46B devices provide dedicated 16-bit communication. Advanced CMOS technology makes these devices ideal for low power, nonvolatile memory applications. The entire 93XX Series is available in standard packages including 8-lead PDIP and SOIC, and advanced packaging including 8-lead MSOP, 6-lead SOT-23, and 8-lead TSSOP. Pb-free (Pure Matte Sn) finish is also available.

### Package Types (not to scale)



# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings<sup>(†)</sup>

V <sub>CC</sub> .....	7.0V
All inputs and outputs w.r.t. V <sub>SS</sub> .....	-0.6V to V <sub>CC</sub> +1.0V
Storage temperature .....	-65°C to +150°C
Ambient temperature with power applied.....	-40°C to +125°C
ESD protection on all pins .....	≥ 4 kV

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**TABLE 1-1: DC CHARACTERISTICS**

All parameters apply over the specified ranges unless otherwise noted.			V <sub>CC</sub> = range by device (see Table on Page 1) Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C				
Param. No.	Symbol	Parameter	Min	Typ	Max	Units	Conditions
D1	V <sub>IH1</sub>	High-level input voltage	2.0	—	V <sub>CC</sub> +1	V	V <sub>CC</sub> ≥ 2.7V
	V <sub>IH2</sub>		0.7 V <sub>CC</sub>	—	V <sub>CC</sub> +1	V	V <sub>CC</sub> < 2.7V
D2	V <sub>IL1</sub>	Low-level input voltage	-0.3	—	0.8	V	V <sub>CC</sub> ≥ 2.7V
	V <sub>IL2</sub>		-0.3	—	0.2 V <sub>CC</sub>	V	V <sub>CC</sub> < 2.7V
D3	V <sub>OL1</sub>	Low-level output voltage	—	—	0.4	V	I <sub>OL</sub> = 2.1 mA, V <sub>CC</sub> = 4.5V
	V <sub>OL2</sub>		—	—	0.2	V	I <sub>OL</sub> = 100 μA, V <sub>CC</sub> = 2.5V
D4	V <sub>OH1</sub>	High-level output voltage	2.4	—	—	V	I <sub>OH</sub> = -400 μA, V <sub>CC</sub> = 4.5V
	V <sub>OH2</sub>		V <sub>CC</sub> - 0.2	—	—	V	I <sub>OH</sub> = -100 μA, V <sub>CC</sub> = 2.5V
D5	I <sub>LI</sub>	Input leakage current	—	—	±1	μA	V <sub>IN</sub> = V <sub>SS</sub> to V <sub>CC</sub>
D6	I <sub>LO</sub>	Output leakage current	—	—	±1	μA	V <sub>OUT</sub> = V <sub>SS</sub> to V <sub>CC</sub>
D7	C <sub>IN</sub> , C <sub>OUT</sub>	Pin capacitance (all inputs/outputs)	—	—	7	pF	V <sub>IN</sub> /V <sub>OUT</sub> = 0V ( <b>Note 1</b> ) TA = 25°C, F <sub>CLK</sub> = 1 MHz
D8	I <sub>CC</sub> write	Write current	—	—	2	mA	F <sub>CLK</sub> = 3 MHz, V <sub>CC</sub> = 5.5V
			—	500	—	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 2.5V
D9	I <sub>CC</sub> read	Read current	—	—	1	mA	F <sub>CLK</sub> = 3 MHz, V <sub>CC</sub> = 5.5V
			—	—	500	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 3.0V
			—	100	—	μA	F <sub>CLK</sub> = 2 MHz, V <sub>CC</sub> = 2.5V
D10	I <sub>CCS</sub>	Standby current	—	—	1	μA	I-Temp
			—	—	5	μA	E-Temp CLK = CS = 0V ORG = DI = V <sub>SS</sub> or V <sub>CC</sub> ( <b>Note 2</b> ) ( <b>Note 3</b> )
D11	V <sub>POR</sub>	V <sub>CC</sub> voltage detect 93AA46A/B/C, 93LC46A/B/C 93C46A/B/C	—	1.5V	—	V	<b>(Note 1)</b>
			—	3.8V	—	V	

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** ORG pin not available on 'A' or 'B' versions.

**3:** READY/ $\overline{\text{BUSY}}$  status must be cleared from DO, see **Section 3.4 "Data Out (DO)"**.

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**TABLE 1-2: AC CHARACTERISTICS**

All parameters apply over the specified ranges unless otherwise noted.			Vcc = range by device (see Table on Page 1) Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			
Param. No.	Symbol	Parameter	Min	Max	Units	Conditions
A1	FCLK	Clock frequency	—	3 2 1	MHz MHz MHz	4.5V ≤ Vcc < 5.5V, 93XX46C only 2.5V ≤ Vcc < 5.5V 1.8V ≤ Vcc < 2.5V
A2	TCKH	Clock high time	200 250 450	—	ns ns ns	4.5V ≤ Vcc < 5.5V, 93XX46C only 2.5V ≤ Vcc < 5.5V 1.8V ≤ Vcc < 2.5V
A3	TCKL	Clock low time	100 200 450	—	ns ns ns	4.5V ≤ Vcc < 5.5V, 93XX46C only 2.5V ≤ Vcc < 5.5V 1.8V ≤ Vcc < 2.5V
A4	TCSS	Chip Select setup time	50 100 250	—	ns ns ns	4.5V ≤ Vcc < 5.5V 2.5V ≤ Vcc < 4.5V 1.8V ≤ Vcc < 2.5V
A5	TCSH	Chip Select hold time	0	—	ns	1.8V ≤ Vcc < 5.5V
A6	TCSL	Chip Select low time	250	—	ns	1.8V ≤ Vcc < 5.5V
A7	TDIS	Data input setup time	50 100 250	—	ns	4.5V ≤ Vcc < 5.5V, 93XX46C only 2.5V ≤ Vcc < 5.5V 1.8V ≤ Vcc < 2.5V
A8	TDIH	Data input hold time	50 100 250	—	ns	4.5V ≤ Vcc < 5.5V, 93XX46C only 2.5V ≤ Vcc < 5.5V 1.8V ≤ Vcc < 2.5V
A9	TPD	Data output delay time	— — —	200 250 400	ns	4.5V ≤ Vcc < 5.5V, CL = 100 pF 2.5V ≤ Vcc < 4.5V, CL = 100 pF 1.8V ≤ Vcc < 2.5V, CL = 100 pF
A10	Tcz	Data output disable time	— —	100 200	ns	4.5V ≤ Vcc < 5.5V, <b>(Note 1)</b> 1.8V ≤ Vcc < 4.5V, <b>(Note 1)</b>
A11	Tsv	Status valid time	—	200 300 500	ns	4.5V ≤ Vcc < 5.5V, CL = 100 pF 2.5V ≤ Vcc < 4.5V, CL = 100 pF 1.8V ≤ Vcc < 2.5V, CL = 100 pF
A12	TWC	Program cycle time	—	6	ms	Erase/Write mode (AA and LC versions)
A13	TWC		—	2	ms	Erase/Write mode (93C versions)
A14	TEC		—	6	ms	ERAL mode, 4.5V ≤ Vcc ≤ 5.5V
A15	TWL		—	15	ms	WRAL mode, 4.5V ≤ Vcc ≤ 5.5V
A16	—	Endurance	1M	—	cycles	25°C, Vcc = 5.0V, <b>(Note 2)</b>

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** This application is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which may be obtained from [www.microchip.com](http://www.microchip.com).

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**FIGURE 1-1: SYNCHRONOUS DATA TIMING**



**TABLE 1-3: INSTRUCTION SET FOR X 16 ORGANIZATION (93XX46B OR 93XX46C WITH ORG = 1)**

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
ERASE	1	11	A5 A4 A3 A2 A1 A0	—	(RDY/ $\overline{BSY}$ )	9
ERAL	1	00	1 0 X X X X	—	(RDY/ $\overline{BSY}$ )	9
EWDS	1	00	0 0 X X X X	—	HIGH-Z	9
EWEN	1	00	1 1 X X X X	—	HIGH-Z	9
READ	1	10	A5 A4 A3 A2 A1 A0	—	D15 - D0	25
WRITE	1	01	A5 A4 A3 A2 A1 A0	D15 - D0	(RDY/ $\overline{BSY}$ )	25
WRAL	1	00	0 1 X X X X	D15 - D0	(RDY/ $\overline{BSY}$ )	25

**TABLE 1-4: INSTRUCTION SET FOR X 8 ORGANIZATION (93XX46A OR 93XX46C WITH ORG = 0)**

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
ERASE	1	11	A6 A5 A4 A3 A2 A1 A0	—	(RDY/ $\overline{BSY}$ )	10
ERAL	1	00	1 0 X X X X X	—	(RDY/ $\overline{BSY}$ )	10
EWDS	1	00	0 0 X X X X X	—	HIGH-Z	10
EWEN	1	00	1 1 X X X X X	—	HIGH-Z	10
READ	1	10	A6 A5 A4 A3 A2 A1 A0	—	D7 - D0	18
WRITE	1	01	A6 A5 A4 A3 A2 A1 A0	D7 - D0	(RDY/ $\overline{BSY}$ )	18
WRAL	1	00	0 1 X X X X X	D7 - D0	(RDY/ $\overline{BSY}$ )	18

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## 2.0 FUNCTIONAL DESCRIPTION

When the  $ORG^*$  pin is connected to  $V_{CC}$ , the (x16) organization is selected. When it is connected to ground, the (x8) organization is selected. Instructions, addresses and write data are clocked into the DI pin on the rising edge of the clock (CLK). The DO pin is normally held in a HIGH-Z state except when reading data from the device, or when checking the  $READY/BUSY$  status during a programming operation. The  $READY/BUSY$  status can be verified during an Erase/Write operation by polling the DO pin; DO low indicates that programming is still in progress, while DO high indicates the device is ready. DO will enter the HIGH-Z state on the falling edge of CS.

### 2.1 Start Condition

The Start bit is detected by the device if CS and DI are both high with respect to the positive edge of CLK for the first time.

Before a Start condition is detected, CS, CLK, and DI may change in any combination (except to that of a Start condition), without resulting in any device operation (READ, WRITE, ERASE, EWEN, EWDS, ERAL, or WRAL). As soon as CS is high, the device is no longer in Standby mode.

An instruction following a Start condition will only be executed if the required opcode, address and data bits for any particular instruction are clocked in.

### 2.2 Data In/Data Out (DI/DO)

It is possible to connect the Data In and Data Out pins together. However, with this configuration it is possible for a "bus conflict" to occur during the "dummy zero" that precedes the READ operation, if A0 is a logic high level. Under such a condition the voltage level seen at Data Out is undefined and will depend upon the relative impedances of Data Out and the signal source driving A0. The higher the current sourcing capability of A0, the higher the voltage at the Data Out pin. In order to limit this current, a resistor should be connected between DI and DO.

## 2.3 Data Protection

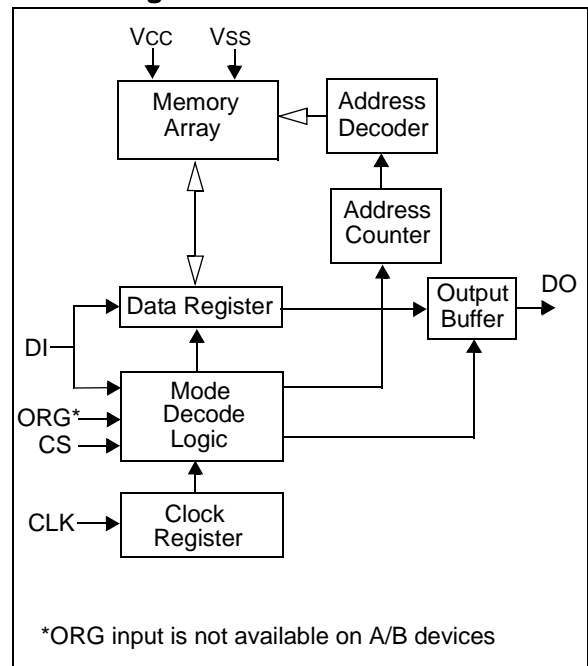
All modes of operation are inhibited when  $V_{CC}$  is below a typical voltage of 1.5V for '93AA' and '93LC' devices or 3.8V for '93C' devices.

The EWEN and EWDS commands give additional protection against accidentally programming during normal operation.

**Note:** For added protection, an EWDS command should be performed after every write operation.

After power-up, the device is automatically in the EWDS mode. Therefore, an EWEN instruction must be performed before the initial ERASE or WRITE instruction can be executed.

### Block Diagram



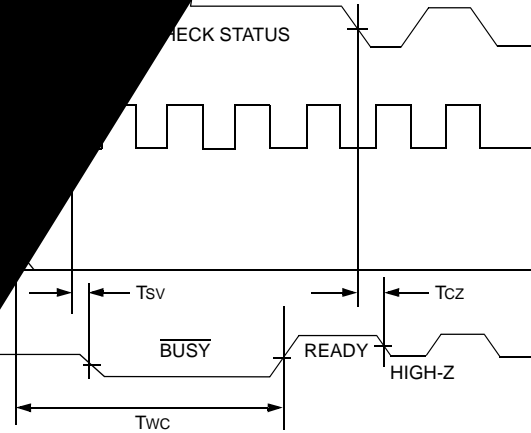
2.4

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s the READY/BUSY status of the nt high after a minimum of 250 ns cal '0' indicates that programming O at logical '1' indicates that the ed address has been erased and r another instruction.

Start bit and then taking CS low the READY/BUSY status from

FIG



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## 2.5 ERASE ALL (ERAL)

The Erase All (ERAL) instruction will erase the entire memory array to the logical '1' state. The ERAL cycle is identical to the ERASE cycle, except for the different opcode. The ERAL cycle is completely self-timed and commences at the falling edge of the CS, except on '93C' devices where the rising edge of CLK before the last data bit initiates the write cycle. Clocking of the CLK pin is not necessary after the device has entered the ERAL cycle.

The DO pin indicates the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status of the device, if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ).

**Note:** Issuing a Start bit and then taking CS low will clear the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status from DO.

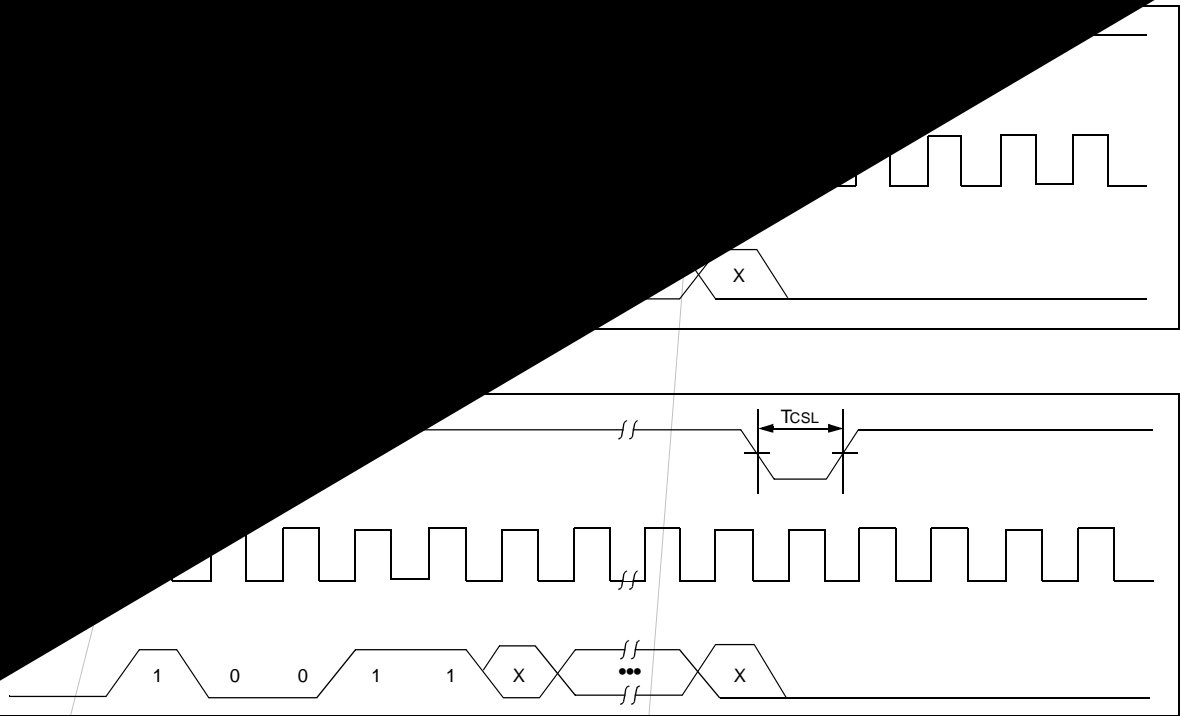
VCC must be  $\geq 4.5\text{V}$  for proper operation of ERAL.

**FIGURE 2-3: ERAL TIMING FOR 93AA AND 93LC DEVICES**



**FIGURE 2-4: ERAL TIMING FOR 93C DEVICES**





## 2.7 READ

the rising edge of the CLK



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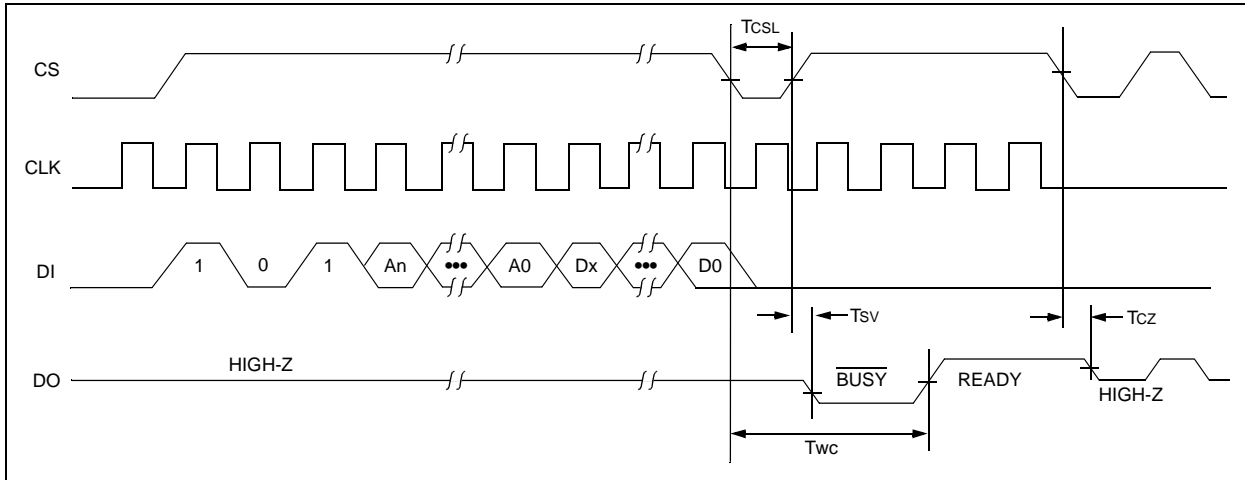
## 2.8 WRITE

The WRITE instruction is followed by 8 bits (If ORG is low or A-version devices) or 16 bits (If ORG pin is high or B-version devices) of data which are written into the specified address. For 93AA46A/B/C and 93LC46A/B/C devices, after the last data bit is clocked into DI, the falling edge of CS initiates the self-timed auto-erase and programming cycle. For 93C46A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit.

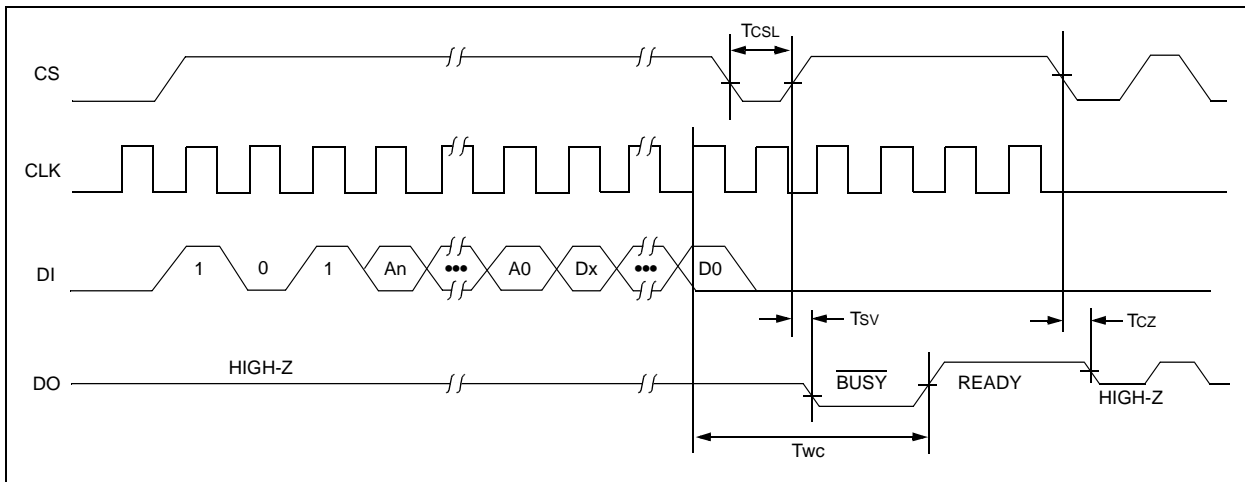
The DO pin indicates the READY/ $\overline{\text{BUSY}}$  status of the device, if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ). DO at logical '0' indicates that programming is still in progress. DO at logical '1' indicates that the register at the specified address has been written with the data specified and the device is ready for another instruction.

**Note:** Issuing a Start bit and then taking CS low will clear the READY/ $\overline{\text{BUSY}}$  status from DO.

**FIGURE 2-8: WRITE TIMING FOR 93AA AND 93LC DEVICES**



**FIGURE 2-9: WRITE TIMING FOR 93C DEVICES**



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## 2.9 WRITE ALL (WRAL)

The Write All (WRAL) instruction will write the entire memory array with the data specified in the command. For 93AA46A/B/C and 93LC46A/B/C devices, after the last data bit is clocked into DI, the falling edge of CS initiates the self-timed auto-erase and programming cycle. For 93C46A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit. Clocking of the CLK pin is not necessary after the device has entered the WRAL cycle. The WRAL command does include an automatic ERAL cycle for the device. Therefore, the WRAL instruction does not require an ERAL instruction but the chip must be in the EWEN status.

The DO pin indicates the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status of the device if CS is brought high after a minimum of 250 ns low ( $T_{\text{CSL}}$ ).

**Note:** Issuing a Start bit and then taking CS low will clear the  $\overline{\text{READY}}/\overline{\text{BUSY}}$  status from DO.

VCC must be  $\geq 4.5\text{V}$  for proper operation of WRAL.

FIGURE 2-10: WRAL TIMING FOR 93AA AND 93LC DEVICES

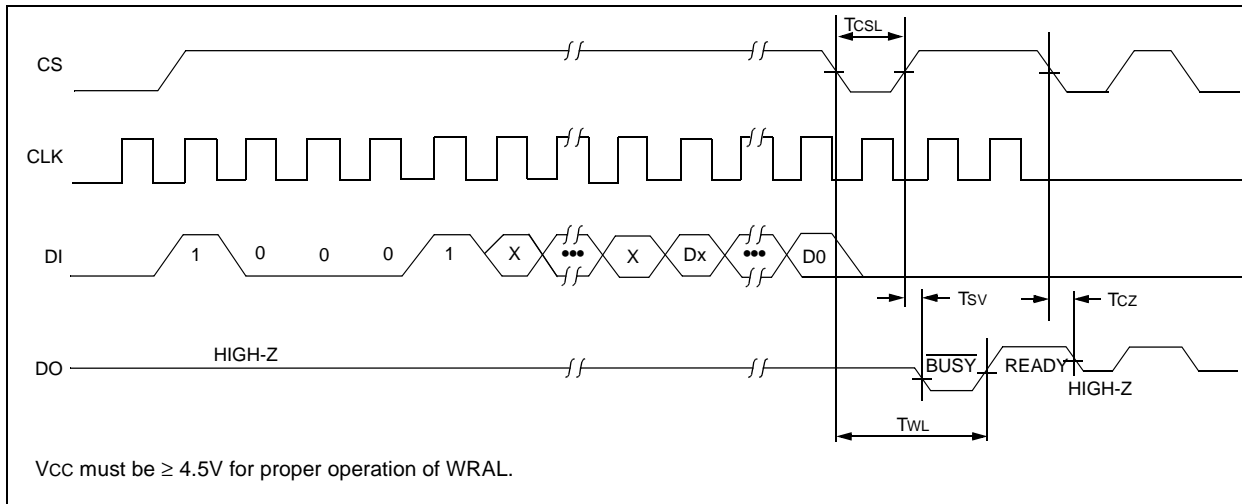
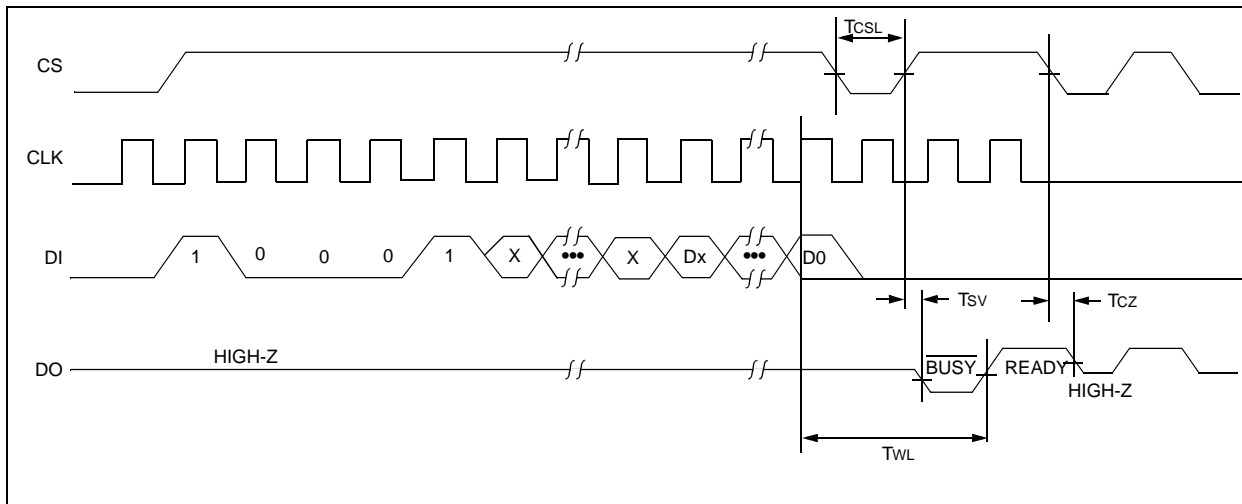


FIGURE 2-11: WRAL TIMING FOR 93C DEVICES



## 3.0 PIN DESCRIPTIONS

TABLE 3-1: PIN DESCRIPTIONS

### 3.1 Chip Select (CS)

A high level selects the device; a low level deselects the device and forces it into Standby mode. However, a programming cycle which is already in progress will be completed, regardless of the Chip Select (CS) input signal. If CS is brought low during a program cycle, the device will go into Standby mode as soon as the programming cycle is completed.

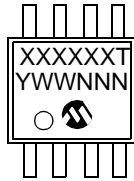
CS must be low for 250 ns minimum (TCSL) between consecutive instructions. If CS is low, the internal

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## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

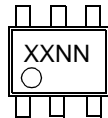
8-Lead MSOP (150 mil)



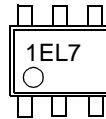
Example:



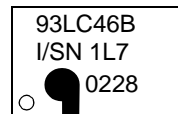
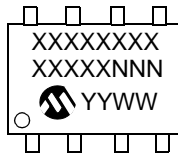
6-Lead SOT-23



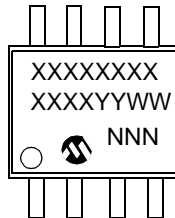
Example:



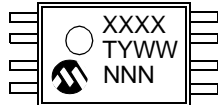
8-Lead PDIP



8-Lead SOIC



8-Lead TSSOP

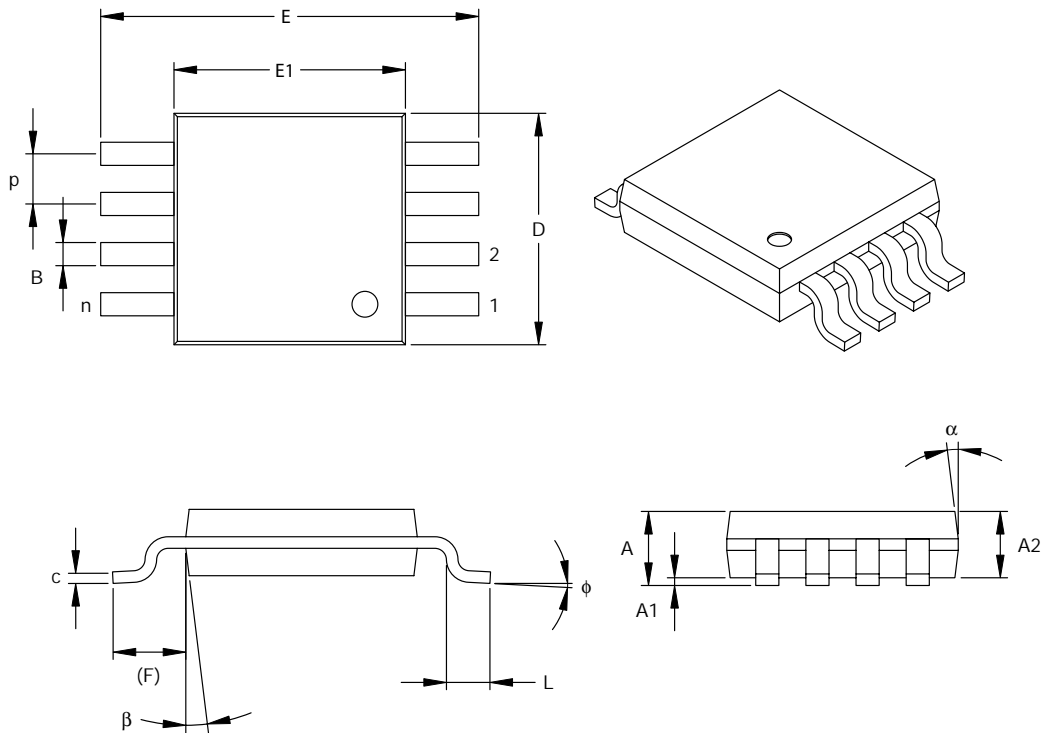


<b>Legend:</b>	XX...X	Part number
	T	Temperature
	Blank	Commercial
	I	Industrial
	E	Extended
	YY	Year code (last 2 digits of calendar year) except TSSOP and MSOP which use only the last 1 digit
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

**Note:** Custom marking available.

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## 8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p	.026 BSC			0.65 BSC		
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E	.193 TYP.			4.90 BSC		
Molded Package Width	E1	.118 BSC			3.00 BSC		
Overall Length	D	.118 BSC			3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F	.037 REF			0.95 REF		
Foot Angle	φ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

\*Controlling Parameter

Notes:

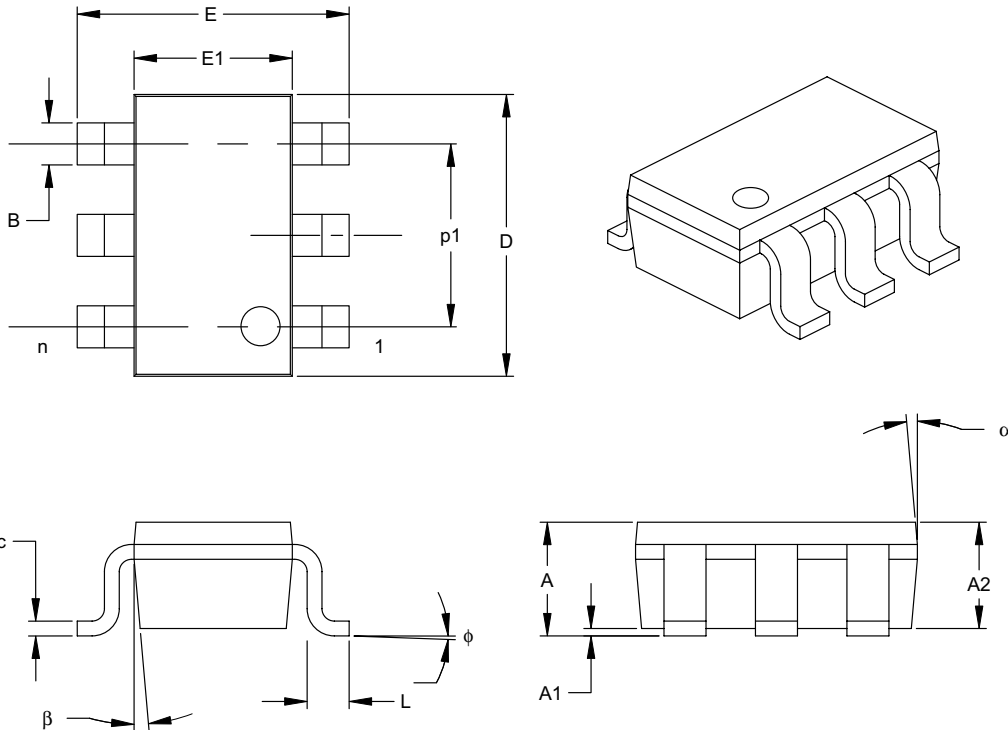
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 6-Lead Plastic Small Outline Transistor (OT) (SOT-23)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		6			6	
Pitch	p		.038			0.95	
Outside lead pitch (basic)	p1		.075			1.90	
Overall Height	A	.035	.046	.057	0.90	1.18	1.45
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30
Standoff	A1	.000	.003	.006	0.00	0.08	0.15
Overall Width	E	.102	.110	.118	2.60	2.80	3.00
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75
Overall Length	D	.110	.116	.122	2.80	2.95	3.10
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	phi	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.014	.017	.020	0.35	0.43	0.50
Mold Draft Angle Top	alpha	0	5	10	0	5	10
Mold Draft Angle Bottom	beta	0	5	10	0	5	10

\*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEITA (formerly EIAJ) equivalent: SC-74A

Drawing No. C04-120

# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

\* Controlling Parameter

§ Significant Characteristic

### Notes:

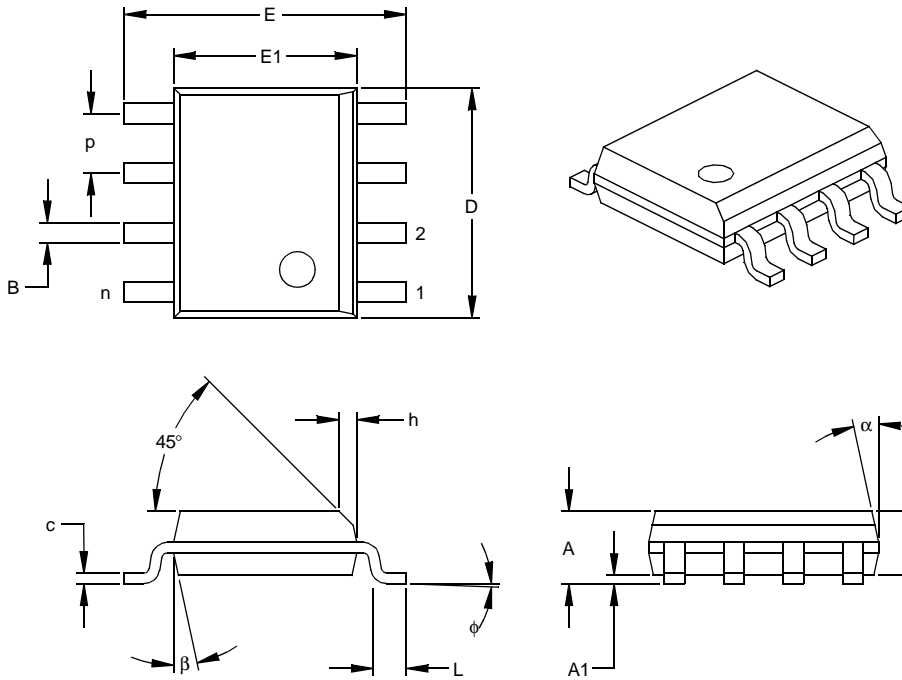
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter

§ Significant Characteristic

### Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057



# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

## 8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

\* Controlling Parameter

§ Significant Characteristic

### Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-086

# 93AA46A/B/C, 93LC46A/B/C, 93C46A/B/C

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## APPENDIX A: REVISION HISTORY

### Revision D

Corrections to Section 1.0, Electrical Characteristics.  
Section 4.1, 6-Lead SOT-23 package to OT.

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